

Appl. No. 10/829,146
Amdt. Dated April 27, 2005
Reply to Office Action of January 27, 2005

Attorney Docket No. 81751.0071
Customer No.: 26021

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently amended) An electronic device comprising:
a semiconductor substrate in which an integrated circuit is formed;
an insulating layer which is formed on the semiconductor substrate and includes has a first upper surface;
an elastically deformable section formed on the first upper surface, the elastically deformable section formed at a position closer to one of edges of the semiconductor substrate than a center of the semiconductor substrate, the elastically deformable section having a second upper surface;
an electrode ~~first and second electrodes~~ which is ~~are~~ electrically connected with ~~an~~ inside of the semiconductor substrate and is, the first electrode being formed on the first upper surface, the second electrode being formed on the elastically deformable section ~~second upper surface; and~~
a first substrate on which a first interconnect pattern is formed, the first interconnect pattern facing the first electrode and being electrically connected with the first electrode; and
a second substrate on which ~~an~~ a second interconnect pattern is formed, the second interconnect pattern facing the ~~second~~ electrode and being electrically connected with the ~~second~~ electrode,
wherein the elastically deformable section is elastically deformed in a manner to be depressed under the second electrode, and presses the second electrode against the second interconnect pattern due to elasticity.

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2. (Currently amended) The electronic device as defined in claim 1, further comprising a bump formed between the second electrode and the second interconnect pattern, the second electrode being electrically connected with the second interconnect pattern through the bump.

3. (Original) The electronic device as defined in claim 2, wherein the bump includes a nickel layer.

4. (Canceled)

5. (Currently amended) A method of manufacturing an electronic device, comprising:

mounting a semiconductor device having first and second electrodes on a substrate first and second substrates on which an interconnect pattern is are formed; and

electrically connecting the first and second electrodes with the first and interconnect patterns, respectively, wherein the semiconductor device includes including:

a semiconductor substrate in which an integrated circuit is formed, the first and second electrodes being electrically connected with an inside of the semiconductor substrate; an insulating layer which is formed on the semiconductor substrate and includes an elastically deformable section, and an electrode which is electrically connected with inside of the semiconductor substrate and is formed on the elastically deformable section, and

an insulating layer which is formed on the semiconductor substrate and has a first upper surface; and

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an elastically deformable section formed on the first upper surface, the elastically deformable section formed at a position closer to one of edges of the semiconductor substrate than a center of the semiconductor substrate, the elastically deformable section having a second upper surface, the first electrode formed on the first upper surface, the second electrode formed on the second upper surface,

wherein, in the mounting step, the semiconductor device and the first and second substrate are disposed so that the electrode first and second electrodes respectively faces the first and second interconnect pattern patterns, and the elastically deformable section is elastically deformed in a manner to be depressed under the second electrode.

6. (Currently amended) The method of manufacturing an electronic device as defined in claim 5,

wherein the semiconductor device further includes a bump formed on the second electrode, and

wherein the elastically deformable section is elastically deformed through the bump.